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Standards

Irish Standard  
I.S. EN 62047-5:2011

Semiconductor devices - Micro-  
electromechanical devices -- Part 5: RF  
MEMS switches (IEC 62047-5:2011  
(EQV))

## I.S. EN 62047-5:2011

*Incorporating amendments/corrigenda issued since publication:*

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<b>NSAI</b> 1 Swift Square, Northwood, Santry Dublin 9	T +353 1 807 3800 F +353 1 807 3838 E standards@nsai.ie  W NSAI.ie	<b>Sales:</b> T +353 1 857 6730 F +353 1 857 6729 W standards.ie
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EUROPEAN STANDARD

**EN 62047-5**

NORME EUROPÉENNE

EUROPÄISCHE NORM

August 2011

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ICS 31.080.99

English version

**Semiconductor devices -  
Micro-electromechanical devices -  
Part 5: RF MEMS switches  
(IEC 62047-5:2011)**

Dispositifs à semiconducteurs -  
Dispositifs microélectromécaniques -  
Partie 5: Commutateurs MEMS-RF  
(CEI 62047-5:2011)

Halbleiterbauelemente -  
Bauelemente der Mikrosystemtechnik -  
Teil 5: Hochfrequenz-MEMS-Schalter  
(IEC 62047-5:2011)

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Management Centre: Avenue Marnix 17, B - 1000 Brussels**

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## **Foreword**

The text of document 47F/83/FDIS, future edition 1 of IEC 62047-5, prepared by SC 47F, Micro-electromechanical systems, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62047-5 on 2011-08-17.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN and CENELEC shall not be held responsible for identifying any or all such patent rights.

The following dates were fixed:

- latest date by which the EN has to be implemented  
at national level by publication of an identical  
national standard or by endorsement (dop) 2012-05-17
- latest date by which the national standards conflicting  
with the EN have to be withdrawn (dow) 2014-08-17

Annex ZA has been added by CENELEC.

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## **Endorsement notice**

The text of the International Standard IEC 62047-5:2011 was approved by CENELEC as a European Standard without any modification.

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60747-1 + corr. August	2006 2008	Semiconductor devices - Part 1: General	-	-
IEC 60747-16-1	-	Semiconductor devices - Part 16-1: Microwave integrated circuits - Amplifiers	EN 60747-16-1	-
IEC 60747-16-4	2004	Semiconductor devices - Part 16-4: Microwave integrated circuits - Switches	EN 60747-16-4	2004
IEC 60749-5	-	Semiconductor devices - Mechanical and climatic test methods - Part 5: Steady-state temperature humidity bias life test	EN 60749-5	-
IEC 60749-10	-	Semiconductor devices - Mechanical and climatic test methods - Part 10: Mechanical shock	EN 60749-10	-
IEC 60749-12	-	Semiconductor devices - Mechanical and climatic test methods - Part 12: Vibration, variable frequency	EN 60749-12	-
IEC 60749-27	-	Semiconductor devices - Mechanical and climatic test methods - Part 27: Electrostatic discharge (ESD) sensitivity testing - Machine model (MM)	EN 60749-27	-

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**SEMICONDUCTOR DEVICES –  
MICRO-ELECTROMECHANICAL DEVICES –**
**Part 5: RF MEMS switches**

## FOREWORD

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International Standard IEC 62047-5 has been prepared by subcommittee 47F: Micro-electromechanical systems, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47F/83/FDIS	47F/93/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 62047 series, under the general title *Semiconductor devices – Micro-electromechanical devices*, can be found in the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
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